

Amendments to the Specification

Please replace the paragraph beginning on page 11, line 26 with the following amended paragraph:

The semiconductor chip 5 has surfaces 51 and 52 opposite to each other, sides 53 and 54 opposite to each other, and sides 55 and 56 opposite to each other. The semiconductor chip 5 has the same shape and size as the semiconductor chip 4. That is, the lengths of the sides 53 and 54 each corresponding to the short side of the semiconductor chip 5 are 7.8mm, and the sides 55 and 56 each corresponding to the long side thereof are 11.4mm. The thickness of the semiconductor chip 5 ranges from 150 μ m to 200 μ m. The semiconductor chip 5 has an electric circuit having the same function as that of the electric circuit of the semiconductor chip 4 and includes an electrode section [[48]] 57 for electrically connecting the electric circuit to the lead terminal section 220. The electrode section 57 is disposed on the side 54 side of the surface 51. The electrode section 57 comprises a plurality of electrodes and is disposed along the side 54.

Please replace the paragraph beginning on page 14, line 6 with the following amended paragraph:

As shown in Fig. 3, an adhesive sheet 6 is bonded onto a surface 201 of a die pad section 200 and an upper surface of a lead terminal section 220 [[200]]. Next, a semiconductor chip 4 is adhered to the die pad section 200 and the lead terminal

section 220 by the adhesive sheet 6 in such a manner that a surface 42 of the semiconductor chip 4 is directed to a surface 201 of the die pad section 200 and a side 43 thereof is located on the side 203 side. At this time, the side 43 of the semiconductor chip 4 is located inside by 0.5mm from the side 203 of the die pad section 200.

Please replace the paragraph beginning on page 20, line 24 with the following amended paragraph:

The semiconductor chip 4 and the support member 300 according to the present embodiment are formed on such a semiconductor wafer W as shown in Fig. 9(a). The semiconductor chip 4 and the support member 300 are formed by being partitioned by scribe lines x_i (where $i = 1, \dots, n, \dots$) and y_j (where $j = 1, \dots, n, \dots$) for separating the semiconductor wafer W into respective chips as shown in ~~the same figure (b)~~ Fig. 9(b).

Please replace the paragraph beginning on page 22, line 20 with the following amended paragraph:

As shown in Fig. 10, an adhesive sheet 6 is adhered to a die pad section 200 and a lead terminal section 220 of a lead frame 2. The integrally-formed semiconductor chip 4 and support member 300 are fixed to the die pad section 200 and lead terminal section 220 by the adhesive sheet 6. At this time, a surface 42 of the semi-conductor chip 4 is placed face to face with a surface ~~[[200]]~~ 201 of the die pad section 200, and a

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side 43 thereof is disposed on the side 203 side of the die pad section 200.